

SEMITRANS<sup>®</sup> 3

**Trench IGBT Modules** 

#### SKM 400GB066D

Preliminary Data

#### Features

- Trench = Trenchgate technology
- V<sub>CE(sat)</sub> with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I<sub>C</sub>

#### **Typical Applications**

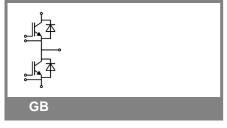
- AC inverter drives
- UPS
- Electronic welders

#### Remarks

- Case temperature limited to  $T_c = 125^{\circ}C$  max, recommended  $T_{op} = -40 \dots +150^{\circ}C$
- Product reliability results are valid for  $T_i \leq 150^{\circ}C$
- Short circuit data:  $t_p \le 6\mu$ s;  $V_{GE} \le 15V$ ;  $T_j = 150^{\circ}$ C;  $V_{cc} \le 360V$ , use of soft  $R_G$  necessary !
- Take care of over-voltage caused by stray inductances

	te Maximum Ratings			
Symbol	Conditions		Values	Units
IGBT				
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		600	V
I <sub>C</sub>	T <sub>j</sub> = 175 °C	T <sub>c</sub> = 25 °C	500	А
		T <sub>c</sub> = 80 °C	380	А
I <sub>CRM</sub>	I <sub>CRM</sub> =2xI <sub>Cnom</sub>		800	А
V <sub>GES</sub>			± 20	V
t <sub>psc</sub>	$V_{CC}$ = 360 V; $V_{GE} \le 15$ V; VCES < 600 V	T <sub>j</sub> = 150 °C	6	μs
Inverse	Diode		•	
I <sub>F</sub>	T <sub>j</sub> = 175 °C	T <sub>c</sub> = 25 °C	450	А
		T <sub>c</sub> = 80 °C	320	А
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		800	А
Module				
I <sub>t(RMS)</sub>			500	А
T <sub>vj</sub>			- 40 +175	°C
T <sub>stg</sub>			- 40 +125	°C
V <sub>isol</sub>	AC, 1 min.		4000	V

Characteristics T <sub>case</sub> =			25°C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
V <sub>GE(th)</sub>	$V_{GE}$ = $V_{CE}$ , $I_C$ = 6,4 mA		5	5,8	6,5	V
I <sub>CES</sub>	$V_{GE}$ = 0 V, $V_{CE}$ = $V_{CES}$	T <sub>j</sub> = 25 °C		0,25	0,75	mA
V <sub>CE0</sub>		T <sub>j</sub> = 25 °C		0,9	1	V
		T <sub>j</sub> = 150 °C		0,85	0,9	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C		1,4	2,3	mΩ
		T <sub>j</sub> = 150°C		2,1	3	mΩ
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 400 A, V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C <sub>chiplev.</sub>		1,45	1,9	V
		T <sub>j</sub> = 150°C <sub>chiplev.</sub>		1,7	2,1	V
C <sub>ies</sub>				24,7		nF
C <sub>oes</sub>	$V_{CE}$ = 25, $V_{GE}$ = 0 V	f = 1 MHz		1,54		nF
C <sub>res</sub>				0,73		nF
$Q_{G}$	V <sub>GE</sub> = -8V+15V			3000		nC
R <sub>Gint</sub>	$T_j = °C$			2		Ω
t <sub>d(on)</sub>				200		ns
t <sub>r</sub>	R <sub>Gon</sub> = 1,5 Ω	V <sub>CC</sub> = 300V		60		ns
Ė <sub>on</sub>	<b>D</b> 450	I <sub>C</sub> = 400A		8		mJ
t <sub>d(off)</sub>	$R_{Goff}$ = 1,5 $\Omega$	$T_{j} = 150 \ ^{\circ}C$		560		ns
t <sub>f</sub>		V <sub>GE</sub> = -8V/+15V		53		ns
E <sub>off</sub>				16		mJ
R <sub>th(j-c)</sub>	per IGBT				0,12	K/W





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GB	

Characteristics						
Symbol	Conditions		min.	typ.	max.	Units
Inverse D	Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom}$ = 400 A; $V_{GE}$ = 0 V	T <sub>j</sub> = 25 °C <sub>chiplev.</sub>		1,4	1,6	V
V <sub>F0</sub>		T <sub>j</sub> = 25 °C		0,95	1	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		1,1	1,5	mΩ
I <sub>RRM</sub>	I <sub>F</sub> = 400 A	T <sub>i</sub> = 150 °C		410		А
Q <sub>rr</sub>	di/dt = 7250 A/µs			62		μC
E <sub>rr</sub>	$V_{GE}$ = -8 V; $V_{CC}$ = 300 V			14		mJ
R <sub>th(j-c)D</sub>	per diode				0,2	K/W
Module						
$L_{CE}$				15	20	nH
R <sub>CC'+EE'</sub>	res., terminal-chip	T <sub>case</sub> = 25 °C		0,35		mΩ
		T <sub>case</sub> = 125 °C		0,5		mΩ
R <sub>th(c-s)</sub>	per module				0,038	K/W
M <sub>s</sub>	to heat sink M6		3		5	Nm
M <sub>t</sub>	to terminals M6		2,5		5	Nm
w					325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.



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-								
	Z <sub>th</sub> Symbol	Conditions	Values	Units				
	Ζ.,							
	Z <sub>Ri</sub>	i = 1	80	mk/W				
2	R <sub>i</sub>	i = 2	22,5	mk/W				
L	R <sub>i</sub>	i = 3	6,4	mk/W				
L	R <sub>i</sub>	i = 4	1,1	mk/W				
L	tau,	i = 1	0,0447	s				
L	tau <sub>i</sub>	i = 2	0,0223	s				
	tau <sub>i</sub>	i = 3	0,0015	s				
	tau <sub>i</sub>	i = 4	0,0002	s				
	Z <sub>Ri</sub>	i = 1	130	mk/W				
	R <sub>i</sub>	i = 2	55	mk/W				
	R <sub>i</sub>	i = 3	12,5	mk/W				
	R	i = 4	2,5	mk/W				
	tau	i = 1	0,054	s				
	tau <sub>i</sub>	i = 2	0,01	s				
	tau <sub>i</sub>	i = 3	0,0015	s				
	tau <sub>i</sub>	i = 4	0,1	s				

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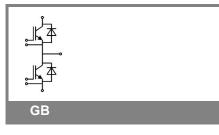
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UL recognized, file no. E 63 532

